

CRUSHABLE BEAD ON LEAD FINGER
SIDE SURFACE TO IMPROVE MOLDABILITY

ABSTRACT OF THE DISCLOSURE

5 A surface mount semiconductor package employs
locking elements for locking a plastic housing to a metal
pad on which a semiconductor device is mounted. The
package includes terminals having elongated crushable
beads on their side surfaces adjacent the portions of the
terminals just outside the plastic housing. The beads
10 are crushed inwardly by a molding tool when it closes to
provide a seal which prevents the molding plastic from
bleeding out and over the sides of the terminals which
extend beyond the housing and which could interfere with
solder connection to the terminals.

Fig. 1